TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSII)

TPC8206

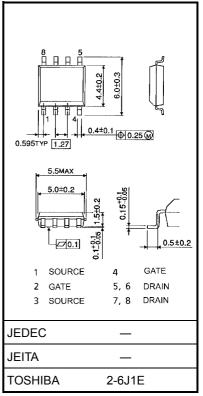
Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

- · Small footprint due to small and thin package
- Low drain-source ON resistance: $RDS(ON) = 40 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 7.0 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 60 \text{ V)}$
- Enhancement-mode: $V_{th} = 1.3 \text{ to } 2.5 \text{ V (VDS} = 10 \text{ V, ID} = 1 \text{ mA)}$

Maximum Ratings (Ta = 25°C)

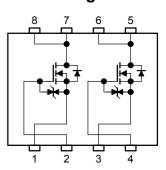
Cha	racteristics	Symbol	Rating	Unit	
Drain-source vo	ain-source voltage		60	V	
Drain-gate volta	rain-gate voltage (R _{GS} = 20 kΩ)		60	V	
Gate-source voltage		V _{GSS}	±20	V	
Orain current Orain power dissipation (t = 10 s) (Note 2a) Orain power	DC (Note 1)	I _D	5	Α	
Dialii Cuileiil	Pulse (Note 1)	I _{DP}	20		
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	1.5		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.0	W	
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	0.75		
dissipation (t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.45	W	
Single pulse avalanche energy (Note 4)		E _{AS}	92	mJ	
Avalanche curre	ent	I _{AR}	5	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.1	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55 to 150	°C	

Unit: mm



Weight: 0.080 g (typ.)

Circuit Configuration



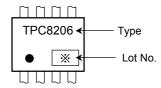
Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
The second resistance of the second second	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	83.3	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	125		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	167		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	278	°C/W	

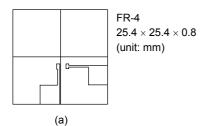
Marking (Note 6)

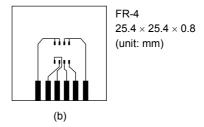


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)





Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)

Note 4: $V_{DD} = 25 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 5.0 mH, $R_G = 25 \Omega$, $I_{AR} = 5 \text{ A}$

Note 5: Repetitive rating; pulse width limited by maximum channel temperature

Note 6: • on lower left of the marking indicates Pin 1.

Weekly code: (Three digits)
 Week of manufacture
 (01 for first week of year, continues up to 52 or 53)
 Year of manufacture
 (One low-order digits of calendar year)

2

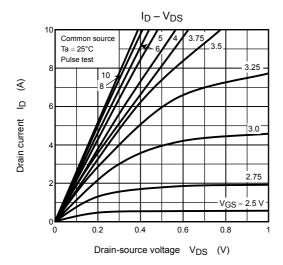
Electrical Characteristics (Ta = 25°C)

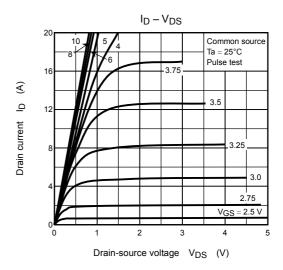
Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$		_	±10	μΑ
Drain cut-OFF cu	ırrent	I _{DSS}	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	10	μΑ
Drain source bro	akdown voltago	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	60	_	_	V
Diain-source bre	akuowii voitage	V _{(BR) DSX}	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	±10 10	V		
Gate threshold voltage		V _{th}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	1.3	_	2.5	٧
Drain aguras ON	una inta una n	Б	$V_{GS} = 4 \text{ V}, I_D = 2.5 \text{ A}$ — $V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}$ —		55	75	mΩ
Drain-source ON	ain-source ON resistance rward transfer admittance out capacitance verse transfer capacitance tput capacitance	KDS (ON)			40	50	
Forward transfer admittance		Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 2.5 \text{ A}$	3.5	7.0	_	S
Input capacitance	е	C _{iss}			800	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		60	_	pF
Output capacitance		Coss		_	190	_	
	Rise time	t _r	10 V 🗖 - 15 - 2.5 A	_	2.6	_	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	_						
	Fall time	t _f	74.7 D	_	2.3	_	ns
	Turn-OFF time	t _{off}		_	22	_	
		Qg	$V_{DD} \simeq 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	17	_	nC
Gate-source charge		Q _{gs}		_	12	_	
Gate-drain ("mille	er") charge	Q _{gd}		_	5	_	

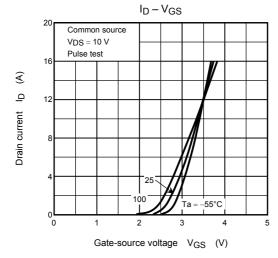
Source-Drain Ratings and Characteristics (Ta = 25°C)

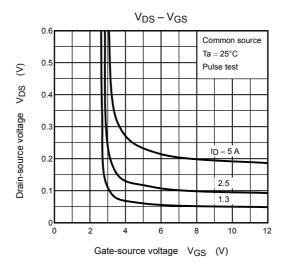
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	20	Α
Forward voltage (diode)		V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.2	V

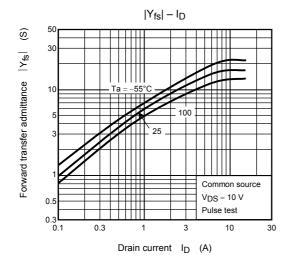
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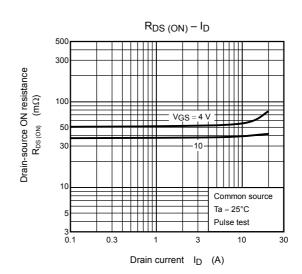


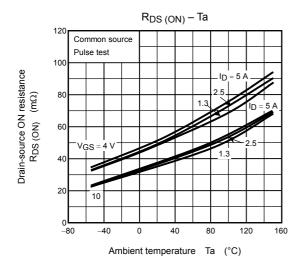


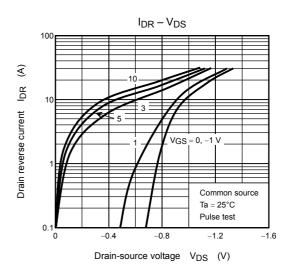


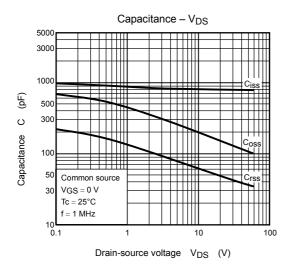


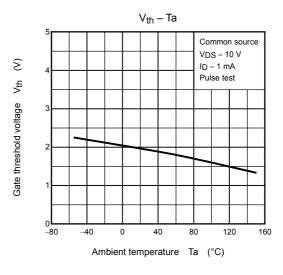


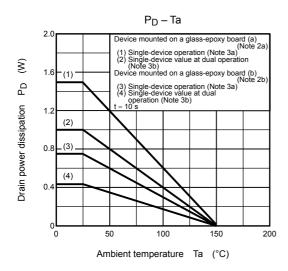


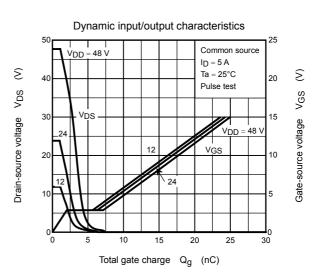


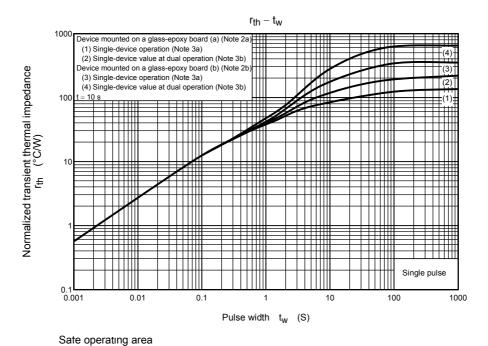


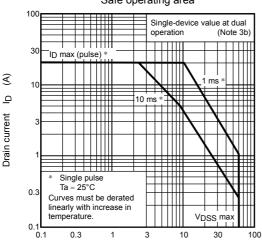












Drain-source voltage V_{DS}

(V)

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6

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